



Dr. Andreas Klipp

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Dr. Andreas Klipp works currently as Global Development Team Leader for Semiconductor Application for Cleaning, Etching and Photo Ancillaries at BASF SE Electronic Materials. His current work at BASF is focused on the development of new cleaning and etch solutions and their product launch for advanced technology nodes 5nm and below.

Before he joined BASF Electronic Materials in November 2006, he worked at Qimonda as R&D project manager. At this time Dr. Klipp was involved in developing new gap-filling deposition processes (wet and chemical vapor deposition techniques) for technology nodes sub 70nm.

Dr. Klipp joined Infineon Technologies in 2000 and worked several years as a process engineer. Mainly he was involved in developing and maintaining of low-k dielectrics (CVD and Spin On), Ozone- and plasma-enhanced CVD TEOS processes.

Dr. Klipp received his PhD in chemistry at the University of Bielefeld in 1999 and is author and co-author of many technical publications and patents.